



## **SPECIFICATION**

(Reference sheet)

• Supplier : Samsung electro-mechanics • Samsung P/N : CL10A226MR8NQNF

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 22 µF, 4V, ±20%, X5R, 0603

## A. Samsung Part Number

<u>CL</u> <u>10</u> <u>A</u> <u>226</u> <u>M</u> <u>R</u> <u>8</u> <u>N</u> <u>Q</u> <u>N</u> <u>F</u> ① ② ③ ④ ⑤ ⑥ ⑦ 8 ⑨ ⑩ ⑪

① Series	Samsung Multi-layer Ceramic Capacitor		
② Size	0603 (inch code)	L: 1.60 ± 0.15 mm	W: 0.80 ± 0.15 mm
③ Dielectric	X5R	8 Inner electrode	Ni
Capacitance	<b>22</b> μF	Termination	Cu
⑤ Capacitance	±20 %	Plating	Sn 100% (Pb Free)
tolerance		Product	Size Control Code
6 Rated Voltage	4 V	10 Special	Reserved for future use
7 Thickness	$0.80 \pm 0.15 \text{ mm}$	Packaging	Embossed Type, 13" reel

## **B. Samsung Reliability Test and Judgement condition**

	Performance	Test condition	
Capacitance	Within specified tolerance	120Hz±20% 0.5±0.1Vrms  *A capacitor prior to measuring the capacitance is heat treated at 150℃+0/-10℃, and maintained in ambient air	
Tan δ (DF)	0.1 max.	for 24±2 hours.	
Insulation	10,000Mohm or 50Mohm⋅μF	Rated Voltage 60~120 sec.	
Resistance	Whichever is Smaller		
Appearance	No abnormal exterior appearance	Microscope (×10)	
Withstanding	No dielectric breakdown or	250% of the rated voltage	
Voltage	mechanical breakdown		
Temperature	X5R		
Characterisitcs	(From -55℃ to 85℃, Capacitance change should be within ±15%)		
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.	
of Termination	terminal electrode		
Bending Strength	Capacitance change: within ±12.5%	Bending to the limit (1mm)	
		with 1.0mm/sec.	
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder	
	is to be soldered newly	245±5℃, 3±0.3sec.	
		(preheating : 80~120 ℃ for 10~30sec.)	
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5℃, 10±1sec.	
Soldering heat	Tan δ, IR : initial spec.		

	Performance	Test condition
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)
		2hours × 3 direction (x, y, z)
Moisture	Capacitance change: within ±12.5%	With rated voltage
Resistance	Tan δ : 0.25 max	40±2℃, 90~95%RH, 500+12/-0hrs
	IR: 500Mohm or 8.8Mohm · μF	
	Whichever is Smaller	
High Temperature	Capacitance change: within ±12.5%	With 100% of the rated voltage
Resistance	Tan δ : 0.25 max	Max. operating temperature
	IR: 1,000Mohm or 17.7Mohm $\cdot \mu$ F	
	Whichever is Smaller	1000+48/-0hrs
Temperature	Capacitance change: within ±10%	1 cycle condition
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25 °C
		$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}$
		5 cycle test

## C. Recommended Soldering method:

Reflow ( Reflow Peak Temperature : 260+0/-5°C, 10sec. Max )



A Product specifications included in the specifications are effective as of March 1, 2013.

Please be advised that they are standard product specifications for reference only.

We may change, modify or discontinue the product specifications without notice at any time.

So, you need to approve the product specifications before placing an order.

Should you have any question regarding the product specifications,

please contact our sales personnel or application engineers.